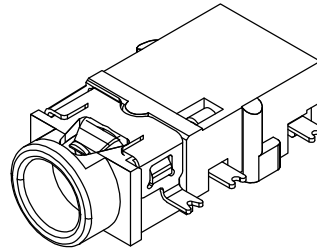


REV.	ECN NO.	DESCRIPTION	DESIGN	DATE
A		INITIAL	Lucky	2018.03.24

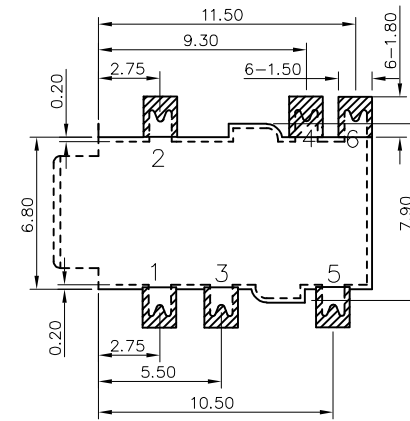
NOTES:

1. REQUEST OF THE SPECIFICATION:

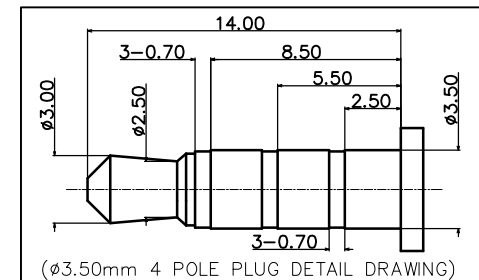
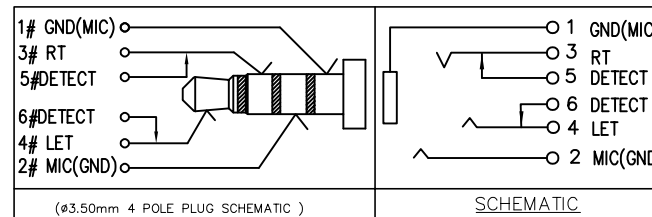
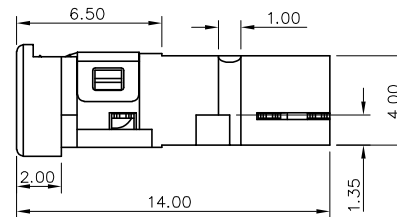
- 1.1 CONTACT CURRENT RATING: 1A.;
- 1.2 CONTACT RESISTANCE: 100 mΩ MAX.;
- 1.3 INSULATION RESISTANCE: 100MΩ MIN.;
- 1.4 DIELECTRIC WITHSTANDING: 500V AC MIN.;
- 1.5 DURABILITY: 5,000 CYCLES MIN.;
- 1.6 CONNECTOR MATING FORCES: 29.8N (3.00Kgf) MAX.;
- 1.7 CONNECTOR UNMATING FORCES: 2.98N(0.30Kgf) MIN.;



3D VIEW



P.C.B LAYOUT
TOP VIEW



ITEM	NAME	Q'TY	DESCRIPTION	NOTE
7	HOUSING	1	PA9T COLOR BLACK	
6	TERMINAL 6#	1	SUS304; NICKEL UNDER PLATING OVERALL,GOLD PLATING ON SOLDER AREA ;GOLD PLATING ON CONTACT AREA	T=0.20
5	TERMINAL 5#	1	SUS304; NICKEL UNDER PLATING OVERALL,GOLD PLATING ON SOLDER AREA ;GOLD PLATING ON CONTACT AREA	T=0.20
4	TERMINAL 4#	1	SUS304; NICKEL UNDER PLATING OVERALL,GOLD PLATING ON SOLDER AREA ;GOLD PLATING ON CONTACT AREA	T=0.20
3	TERMINAL 3#	1	SUS304; NICKEL UNDER PLATING OVERALL,GOLD PLATING ON SOLDER AREA ;GOLD PLATING ON CONTACT AREA	T=0.20
2	TERMINAL 2#	1	PHOSPHOR BRONZE; NICKEL UNDER PLATING OVERALL,GOLD PLATING ON SOLDER AREA ;GOLD PLATING ON CONTACT AREA	T=0.20
1	TERMINAL 1#	1	SUS304; NICKEL UNDER PLATING OVERALL,GOLD PLATING ON SOLDER AREA ;GOLD PLATING ON CONTACT AREA	T=0.20

UNLESS OTHERWISE
SPECIFIED TOLERANCES

DIM	TOL	DIM	TOL
X.	±0.35	X.	±2°
X.X	±0.30	X.X	±1°
X.XX	±0.20	X.XX	
X.XXX	±0.10	X.XXX	

XB 东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

DWG NO.	Q/XM-CP-RD-0173	PART NAME:	PHONE JACK
DESIGN:	Kai	PART NO.	XB-PJ35A028-F06J1BR-A
CHECK:	/	REV.	A
APPROVED	Lucky	UNIT:	mm
	2018.03.24	SHEET:	1/1